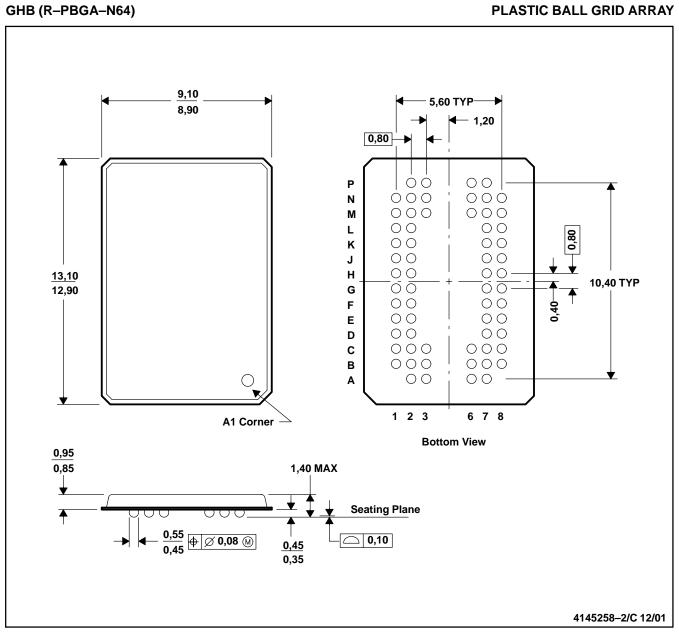
MECHANICAL DATA

MPBG031B FEBRUARY 1997 - REVISED MAY 2002



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice
 - C. MicroStar BGA configuration.



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